

JEDEC STANDARD

Mark Permanency

JESD22-B107D

(Revision of JESD22-B107C, September 2004)

MARCH 2011

JEDEC SOLID STATE TECHNOLOGY ASSOCIATION



NOTICE

JEDEC standards and publications contain material that has been prepared, reviewed, and approved through the JEDEC Board of Directors level and subsequently reviewed and approved by the JEDEC legal counsel.

JEDEC standards and publications are designed to serve the public interest through eliminating misunderstandings between manufacturers and purchasers, facilitating interchangeability and improvement of products, and assisting the purchaser in selecting and obtaining with minimum delay the proper product for use by those other than JEDEC members, whether the standard is to be used either domestically or internationally.

JEDEC standards and publications are adopted without regard to whether or not their adoption may involve patents or articles, materials, or processes. By such action JEDEC does not assume any liability to any patent owner, nor does it assume any obligation whatever to parties adopting the JEDEC standards or publications.

The information included in JEDEC standards and publications represents a sound approach to product specification and application, principally from the solid state device manufacturer viewpoint. Within the JEDEC organization there are procedures whereby a JEDEC standard or publication may be further processed and ultimately become an ANSI standard.

No claims to be in conformance with this standard may be made unless all requirements stated in the standard are met.

Inquiries, comments, and suggestions relative to the content of this JEDEC standard or publication should be addressed to JEDEC at the address below, or refer to www.jedec.org under Standards and Documents for alternative contact information.

Published by
©JEDEC Solid State Technology Association 2011
3103 North 10th Street
Suite 240 South
Arlington, VA 22201-2107

This document may be downloaded free of charge; however JEDEC retains the copyright on this material. By downloading this file the individual agrees not to charge for or resell the resulting material.

PRICE: Contact JEDEC

Printed in the U.S.A.
All rights reserved

PLEASE!

DON'T VIOLATE
THE
LAW!

This document is copyrighted by JEDEC and may not be reproduced without permission.

Organizations may obtain permission to reproduce a limited number of copies through entering into a license agreement. For information, contact:

JEDEC Solid State Technology Association
3103 North 10th Street
Suite 240 South
Arlington, VA 22201-2107

or refer to www.jedec.org under Standards and Documents for alternative contact information.

TEST METHOD B107D

MARK PERMANENCY

(From JEDEC Board Ballot JCB-11-19, formulated under the cognizance of the JC-14.1 Subcommittee on Reliability Test Methods for Packaged Devices.)

1 Scope

The tests mentioned herein are applicable for all package types. They are suitable for use in qualification and/or process monitor testing. The mechanical shear test (tape test) is recommended as an ongoing process monitor or lot acceptance test. Electrical or mechanical rejects may be used for these tests.

NOTE 1 This procedure does not apply to laser marked packages.

NOTE 2 The formulation of solvents herein is considered typical and representative of the desired stringency as far as the usual coatings and marks are concerned. Many available solvents that could be used are either insufficiently active, too stringent, or even dangerous to humans when in direct contact or when the fumes are inhaled.

NOTE 3 These tests should be considered a destructive test unless determined to be non destructive by previous evaluation.

The purpose of this test is to determine whether the marks on solid state semiconductor devices will remain legible (as defined per JESD22B-114) when subjected to the application and removal of labels or the use of solvents and cleaning solutions commonly used during the removal of solder flux residue from the printed circuit board manufacturing process.

2 References

Normative Reference

JESD22B-114, *Mark Legibility*.

Informative Reference

Mil-Std-883, Method 2015, *Resistance to Solvents*. ASTM D3359-95A, *Standard Test Methods for Measuring Adhesion by Tape Test*.